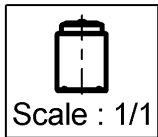
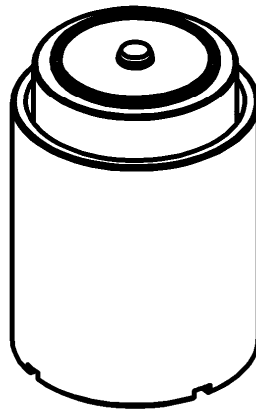
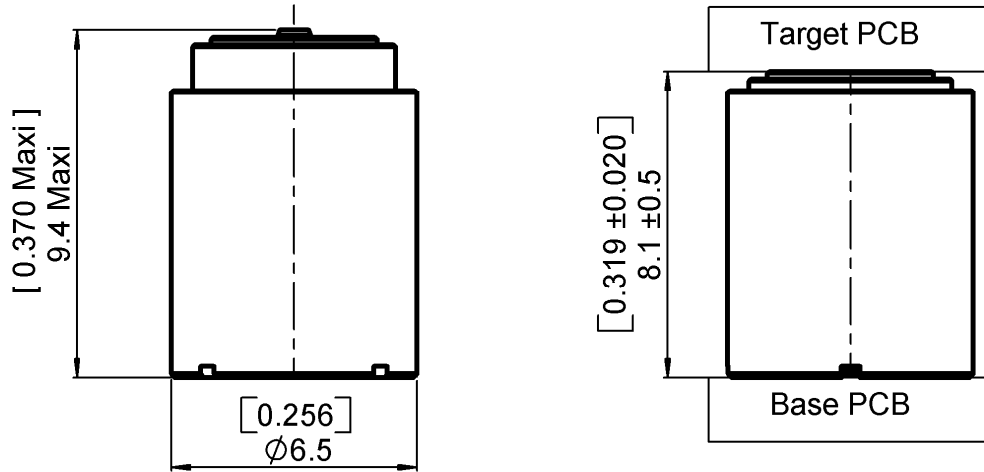


SMT BOARD TO BOARD ADAPTOR

R107.184.000

Series : IMP

Assembly between PCB



All dimensions are in mm / inches.



COMPONENTS	MATERIALS	THICKNESS AND PLATING (µm)
BODY	BERYLLIUM COPPER,BRASS	GOLD 0.5 OVER NICKEL 2
CENTER CONTACT	BERYLLIUM COPPER,BRASS	GOLD 0.2 OVER NICKEL 2
OUTER CONTACT	-	-
INSULATOR	PTFE+PEEK	-
GASKET	-	-
OTHERS PARTS	-	-
-	-	-
-	-	-

Issue : 0843 A

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



SMT BOARD TO BOARD ADAPTOR

R107.184.000

Series : IMP

PACKAGING

SPECIFICATION

Standard	Unit	Other
100	'W' option	Contact us

ELECTRICAL CHARACTERISTICS

ENVIRONMENTAL

Impedance	50	Ω
Frequency	0-18	GHz
VSWR	* + 0,0000	x F(GHz) Maxi
Insertion loss	0.2	\sqrt{F} (GHz) dB Maxi
RF leakage	- (**)	- F(GHz)) dB Maxi
Voltage rating	100	Veff Maxi
Dielectric withstanding voltage	350	Veff mini
Insulation resistance	3000	M Ω mini

Operating temperature	-50/+125	$^{\circ}$ C
Hermetic seal	NA	Atm.cm3/s
Panel leakage	NA	

OTHER CHARACTERISTICS

Assembly instruction

Others :

*VSWR : 1.2 => DC – 6 GHz
 1.3=> 6 – 12.4 GHz
 1.5 => 12.4 – 18 GHz

** RF leakage : -40 dB => DC – 3 GHz
 -20 dB => 6 – 12.4 GHz
 -10 dB => 12.4 – 18 GHz

MECHANICAL CHARACTERISTICS

Center contact retention		
Axial force – Mating end	NA	N mini
Axial force – Opposite end	NA	N mini
Torque	NA	N.cm mini

Recommended torque		
Mating	NA	N.cm
Panel nut	NA	N.cm

Mating life	50	Cycles mini
Weight	1,3100	g

Issue : 0843 A

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SMT BOARD TO BOARD ADAPTOR

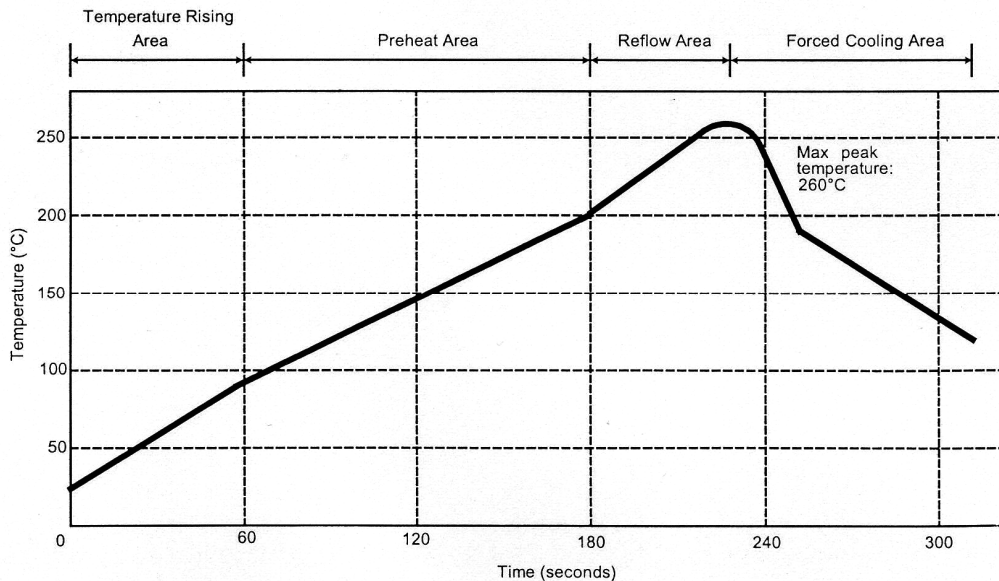
R107.184.000

Series : IMP

SOLDER PROCEDURE

1. Deposit solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application.
We recommend a low residue flux.
We advise a thickness of 150 microns (5.850 microinch). Verify that the edges of the zone are clean.
2. Place the receptacle on the mounting zone with an automatic machine of 'pick and place' type.
Video camera is recommended for the positioning of the component. Adhesive agents must not be used on the receptacle.
3. This process of soldering has been tested with convection oven.
Below please find, the typical profile to use.
4. Clean printed circuit boards.
5. Check solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parmeter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

Issue : 0843 A

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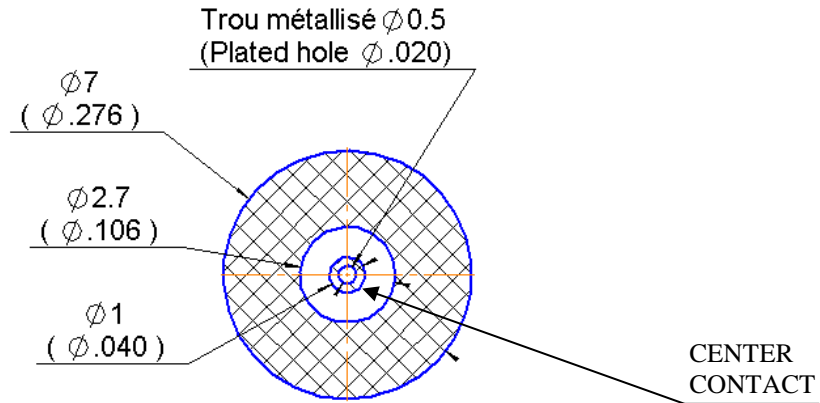
SMT BOARD TO BOARD ADAPTOR


R107.184.000

Series : IMP

PCB base board

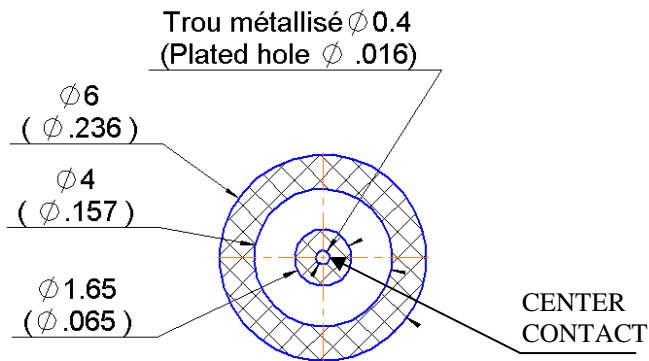
All dimension are in mm / inches




 Nickel doré avec brasure
(Gold over nickel for solder paste)

Vias and transmission line inside PCB are not represented.
The impedance of the transmission line should be 50 ohms

PCB target board



 Nickel doré avec brasure
(Gold over nickel for solder paste)

Vias and transmission line inside PCB are not represented.
The impedance of the transmission line should be 50 ohms

Issue : 0843 A

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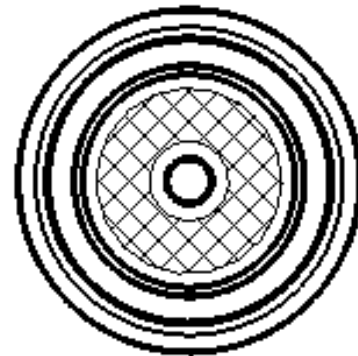
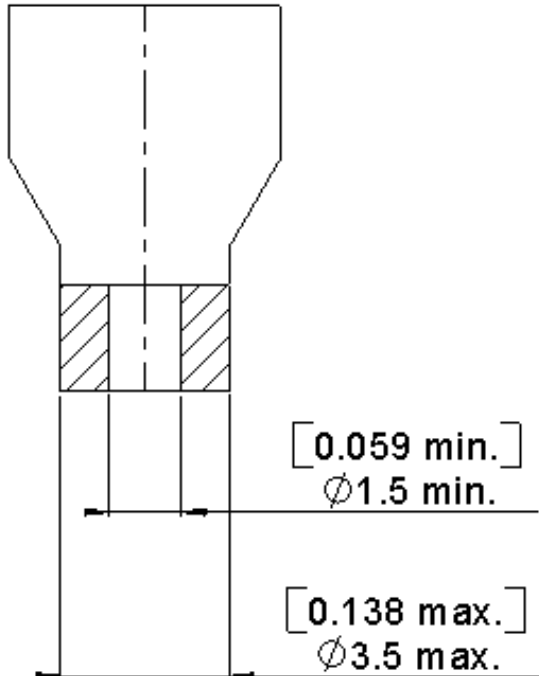


SMT BOARD TO BOARD ADAPTOR

R107.184.000

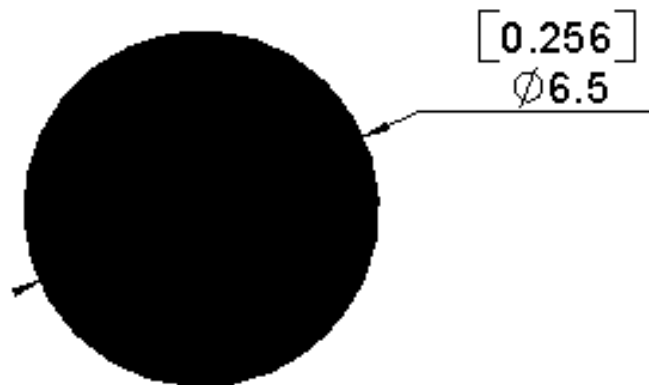
Series : IMP

ASPIRATION PORT



ASPIRATION AREA

SHADOW FOR VIDEO CAMERA



Issue : 0843 A

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